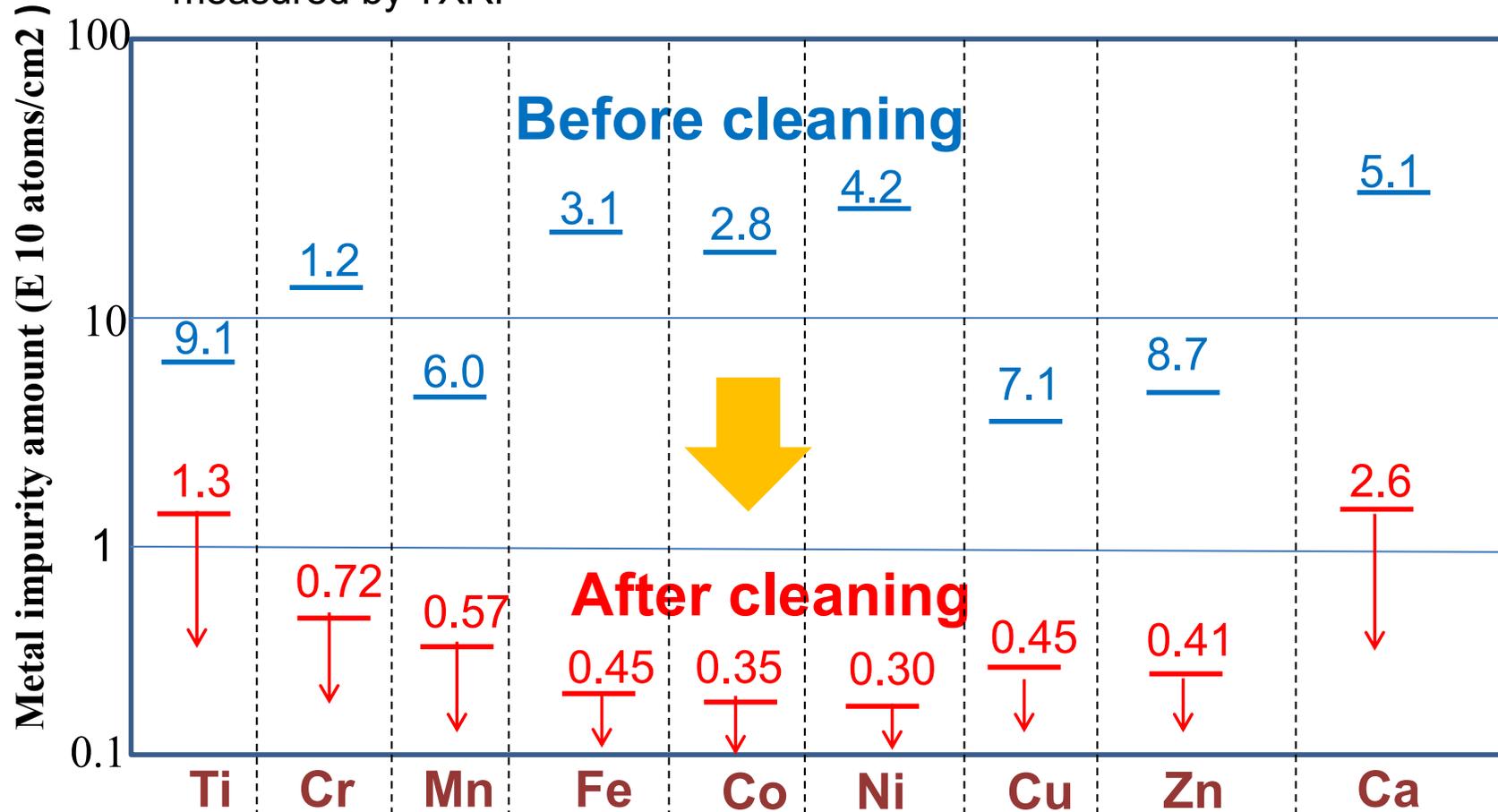


# Metal impurity cleaning result

【Cleaning method】

O3 water(25ppm,30sec.) +0.5%HF(15sec.)

MTK single wafer spin cleaning equipment (MTK) 。 6inch SiC wafer  
measured by TXRF



After cleaning , all metal elements were detected below measure detection limit.